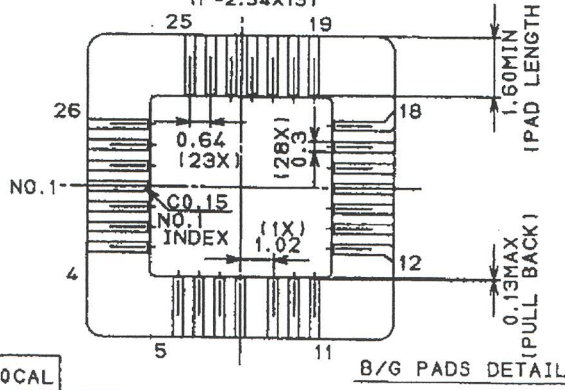
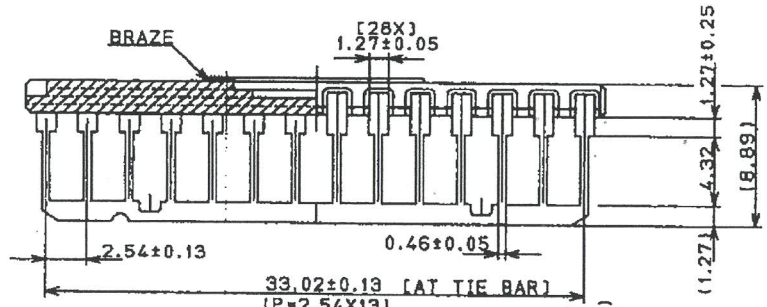
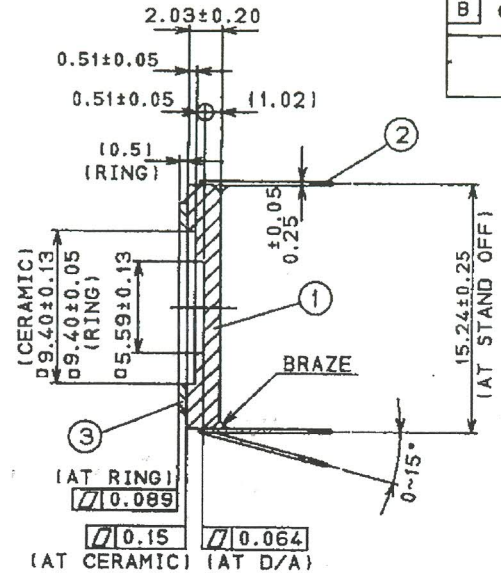
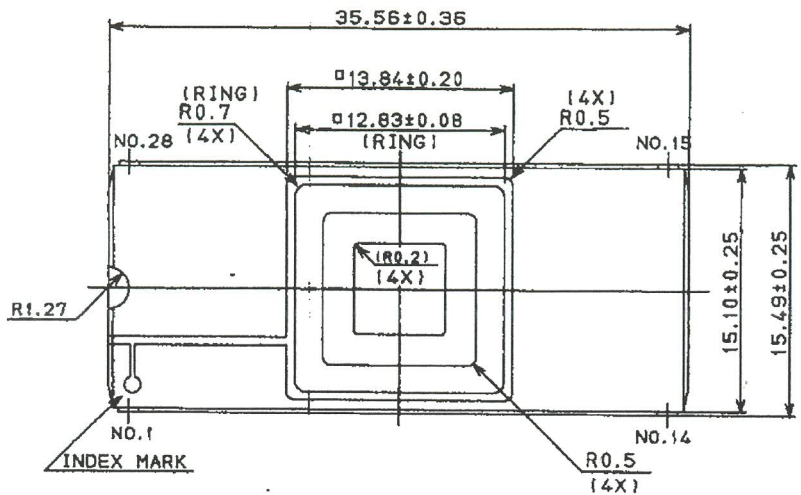


LATEST REVISION'S DESCRIPTION	
B	CHG. LEAD DESIGN.



- NOTES:
1. GOLD PLATE 1.5~5.7 μ m OVER 2.0~6.4 μ m NICKEL.
 2. LEAD RESISTANCE: 500m Ω MAX.
 3. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED.

3 SEAL RING COVER		B RE DRAWING	OCT-17-2005
2 LEAD	ALLOY42	A RE DRAWING	MAR-24-1999
1 CERAMIC	BLACK ALUMINA	NEW DRAWING	MAR-17-1999
Rev.	Description	Rev.	Description
DATE OF REVISION SPECIFIED	BY	DATE	BY
1.0	C. MATSUURA		NTK
1.1	M. NAKAYAMA		NGK SPARK PLUG CO., LTD.
1.2	T. NOMURA		TITLE
ONLY MM			28LD S/B PKG
SCALE		DWG NO.	IDK28F2-620E

MODIFIED DWG NO. IDK28F2-620CAL

B/G PADS DETAIL